

## ATM-3000

## **Automatic Wafer Lamination System**

## **Outline**

The ATM-3000 is the ideal system for laminating tape to wafers, before the backgrind process.

## Features

State-of -the -art design to maintain the integrity of the lamination area and to achieve the best footprint.

Ergonomic design for optimum access to operator areas and service areas on the system

Tape stretch data control.

Ease of operation

FOUP option

AGV and OHT protocol options

Applicable to 8"and 12" dia-wafer



Specification		ATM-3000
Throughput		70 wafers/hour ( Depend on data setting )
Wafer Size		8 inch、12 inch
Tape Width		8 inch : W 230mm 、 12 inch : W 330mm
Utilities	Power	AC100V Single phase 50 / 60Hz 3.0 KVA
	Air	Pressure 0.4Mpa 100NI/min
	Vacuum sourse	74Кра
Dimensions		D 1,575 × W 1,350 × H 1,800mm
Weight		600 kg

System appearance and specifications are subject to change without prior notice from the supplier.

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